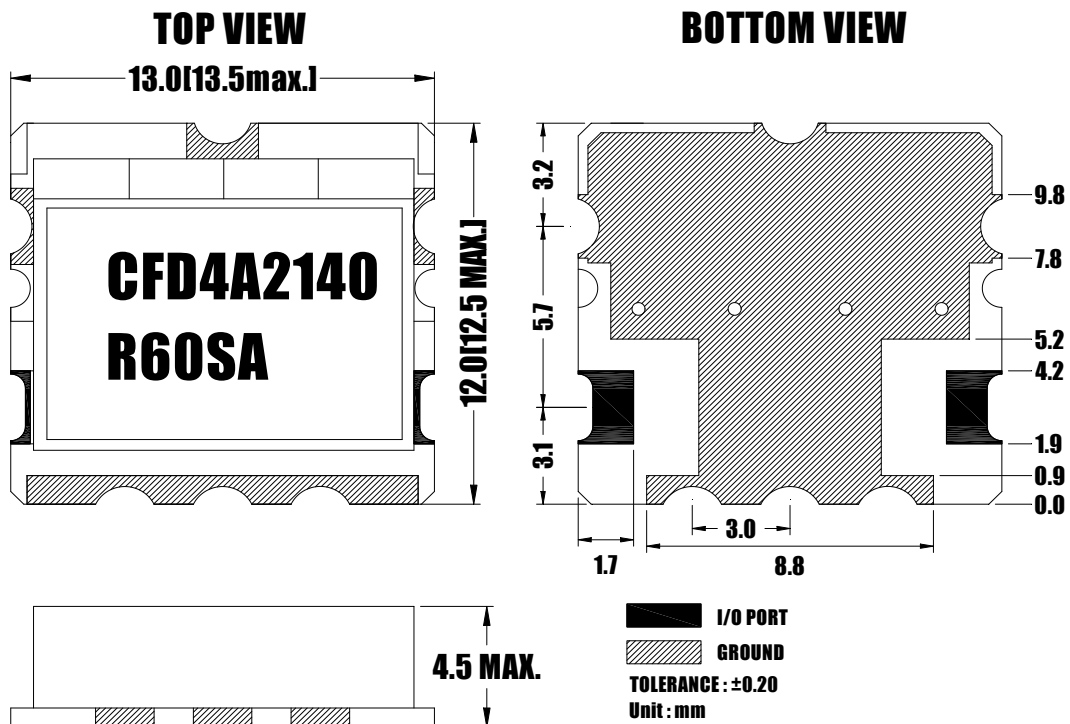


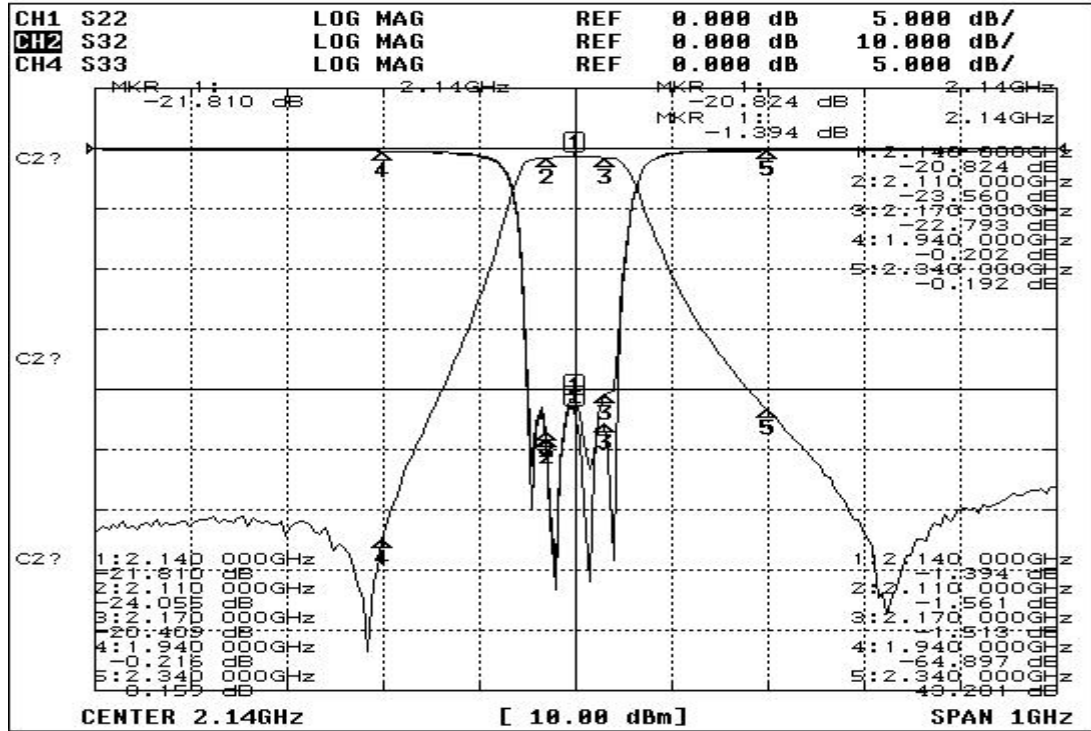
Electrical Specification

| ITEMS | SPEC | UNIT |
|--|------------------------------------|--------|
| Center Frequency [fo] | 2140 | MHz |
| Bandwidth [BW] | fo ± 30 [2110 ~ 2170] | MHz |
| Insertion Loss in BW | 2.2 | dB max |
| Ripple in BW | 0.6 | dB max |
| Return Loss in BW | 15.0 | dB min |
| Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value | 40dB min @ fo ±200 [1940 ~ 2340] | MHz |
| | 35dB min @ [4280] | MHz |
| | dB min @ fo ± [~] | MHz |
| | dB min @ fo ± [~] | MHz |
| Group Delay Variation | | ns max |
| Input Power | | W max. |
| In/Out Impedance | 50 Ω | |
| Operation Temperature Range | -40°C to +85°C | |

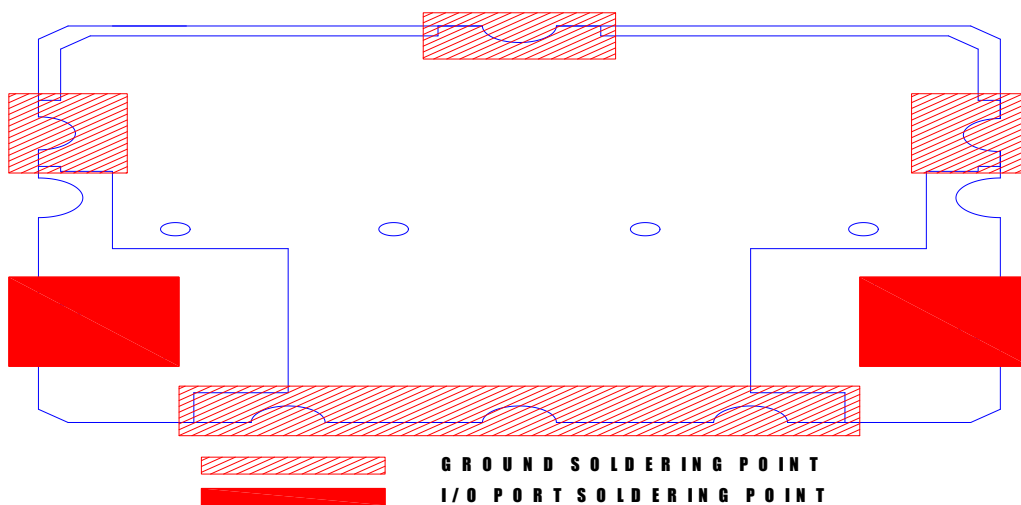
Mechanical Specification



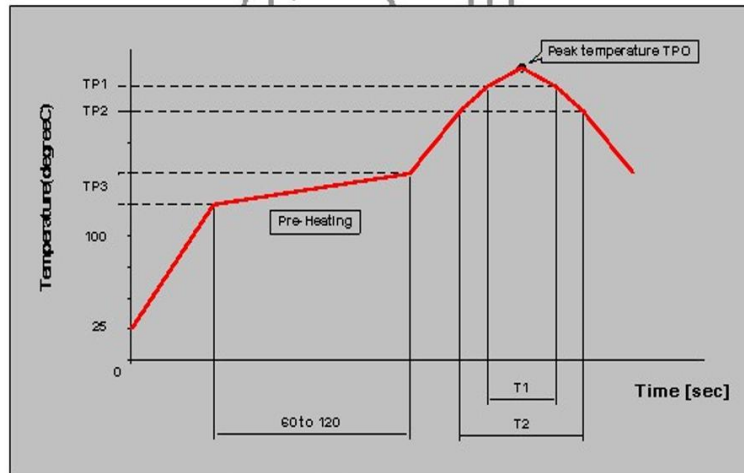
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

| Reflow standard condition | TPO (°C) | TP1 (°C) | T1 (s) | TP2 (°C) | T2 (s) | TP3 (°C) |
|--|----------|----------|----------|----------|--------|------------|
| Sn-3Ag-0.5 solder | 245±5 | 220 | 30 to 60 | — | — | 150 to 180 |
| Test condition of reflow heat resistance | 260±5/0 | 240 | 20 | 220 | 70 | 150 to 180 |